

FGPF50N33BT **330V, 50A PDP IGBT**

Features

- · High current capability
- Low saturation voltage: $V_{CE(sat)} = 1.6V @ I_C = 50A$
- · High input impedance
- Fast switching

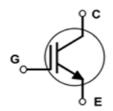
General Description

Using Novel Trench IGBT Technology, Fairchild's new series of trench IGBTs offer the optimum performance for PDP applications where low conduction and switching losses are essential.

Applications

PDP System





Absolute Maximum Ratings

| Symbol | Description | | Ratings | Units | |
|--------------------------|---|-------------------------|-------------|-------|--|
| V _{CES} | Collector to Emitter Voltage | | 330 | V | |
| V _{GES} | Gate to Emitter Voltage | | ± 30 | V | |
| I _C | Collector Current | @ T _C = 25°C | 50 | А | |
| I _{Cpulse (1)*} | Pulsed Collector Current | $@ T_C = 25^{\circ}C$ | 120 | А | |
| I _{Cpulse (2)*} | Pulsed Collector Current | @ T _C = 25°C | 160 | А | |
| P _D | Maximum Power Dissipation | $@ T_C = 25^{\circ}C$ | 43 | W | |
| l D | Maximum Power Dissipation | $@ T_C = 100^{\circ}C$ | 17.2 | W | |
| T _J | Operating Junction Temperature | | -55 to +150 | °C | |
| T _{stg} | Storage Temperature Range | | -55 to +150 | °C | |
| T _L | Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds | | 300 | °C | |

Thermal Characteristics

| Symbol Parameter | | Тур. | Max. | Units | |
|-----------------------|--|------|------|-------|--|
| $R_{\theta JC}(IGBT)$ | Thermal Resistance, Junction to Case - 2 | | 2.9 | °C/W | |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | - | 62.5 | °C/W | |

- 1: Repetitive test , Pulse width=100usec , Duty=0.1 2: Half Sine Wave, D < 0.01, pluse width < 10usec *lc_pluse limited by max Tj

Package Marking and Ordering Information

| Device Marking | Device | Package | Eco Status | Packaging Type | Qty per Tube |
|----------------|---------------|---------|------------|-------------------|--------------|
| FGPF50N33BT | FGPF50N33BTTU | TO-220F | RoHS | Tube | 50ea |



For Fairchild's definition of "green" Eco Status, please visit:

Electrical Characteristics of the IGBT $T_C = 25^{\circ}\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Units |
|--------------------------------|--|---|------|------|------|-------|
| Off Charac | teristics | | | | | |
| BV _{CES} | Collector to Emitter Breakdown Voltage | $V_{GE} = 0V$, $I_{C} = 250\mu A$, $Tc=25^{\circ}C$ | 330 | - | - | V |
| | | $V_{GE} = 0V$, $I_{C} = 250\mu A$, $Tc=125^{\circ}C$ | 340 | - | - | V |
| $\Delta BV_{CES} \ \Delta T_J$ | Temperature Coefficient of Breakdown Voltage | V _{GE} = 0V, I _C = 250μA | - | 0.2 | - | V/°C |
| I _{CES} | Collector Cut-Off Current | $V_{CE} = V_{CES}$, $V_{GE} = 0V$, $Tc=25^{\circ}C$ | - | - | 20 | μА |
| | | $V_{CE} = V_{CES}$, $V_{GE} = 0V$, $Tc=125$ °C | = | - | 200 | μА |
| I _{GES} | G-E Leakage Current | $V_{GE} = V_{GES}, V_{CE} = 0V$ | - | - | ±200 | nA |
| On Charac | teristics | • | | • | • | |
| V _{GE(th)} | G-E Threshold Voltage | $I_C = 250 \mu A, V_{CE} = V_{GE}$ | 2.3 | 3.3 | 4.3 | V |
| | | $I_C = 20A, V_{GE} = 15V,$ | - | 1.2 | 1.5 | V |
| | | $I_C = 30A, V_{GE} = 15V,$ | - | 1.3 | - | V |
| V _{CE(sat)} | Collector to Emitter Saturation Voltage | $I_C = 50A, V_{GE} = 15V,$ $T_C = 25^{\circ}C$ | - | 1.6 | - | V |
| | | I _C = 50A, V _{GE} = 15V, T _C = 125°C | - | 1.7 | - | V |
| Dvnamic C | Characteristics | , | | | | II. |
| C _{ies} | Input Capacitance | | - | 980 | - | pF |
| C _{oes} | Output Capacitance | $V_{CE} = 30V, V_{GE} = 0V,$ | - | 70 | - | pF |
| C _{res} | Reverse Transfer Capacitance | f = 1MHz | = | 40 | - | pF |
| Switching | Characteristics | | | | 1 | |
| t _{d(on)} | Turn-On Delay Time | | - | 9 | - | ns |
| t _r | Rise Time | $V_{CC} = 200V, I_C = 20A,$ | - | 33 | - | ns |
| t _{d(off)} | Turn-Off Delay Time | $R_G = 5\Omega$, $V_{GE} = 15V$, Resistive Load, $T_C = 25^{\circ}C$ | - | 32 | - | ns |
| t _f | Fall Time | | - | 202 | - | ns |
| t _{d(on)} | Turn-On Delay Time | | - | 9 | - | ns |
| t _r | Rise Time | $V_{CC} = 200V, I_C = 20A,$ | - | 37 | - | ns |
| t _{d(off)} | Turn-Off Delay Time | $R_G = 5Ω$, $V_{GE} = 15V$, Resistive Load, $T_C = 125$ °C | - | 33 | - | ns |
| t _f | Fall Time | | - | 332 | - | ns |
| Q _g | Total Gate Charge | | - | 35 | - | nC |
| Q _{ge} | Gate to Emitter Charge | $V_{CE} = 200V, I_{C} = 20A,$ $V_{GE} = 15V$ | - | 6 | - | nC |
| Q _{gc} | Gate to Collector Charge | ▼GE - 13 V | - | 14 | - | nC |

Figure 1. Typical Output Characteristics

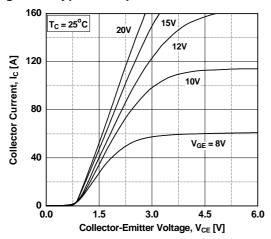


Figure 3. Typical Saturation Voltage Characteristics

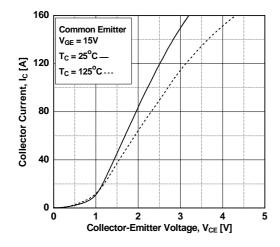


Figure 5. Saturation Voltage vs. Case

Temperature at Variant Current Level

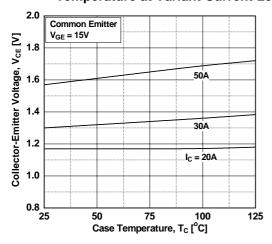


Figure 2. Typical Output Characteristics

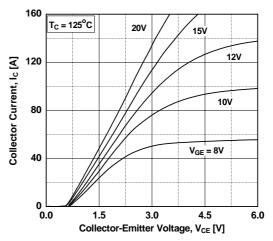


Figure 4. Transfer Characteristics

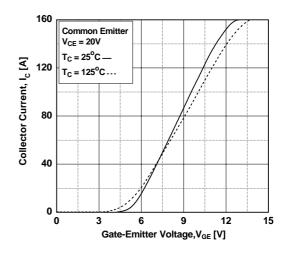


Figure 6. Saturation Voltage vs. V_{GE}

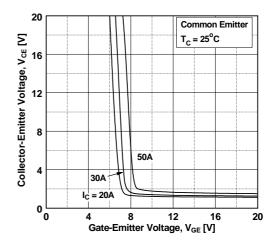


Figure 7. Saturation Voltage vs. V_{GE}

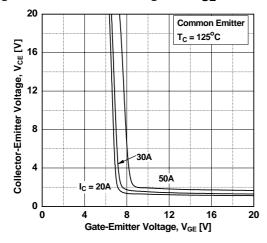


Figure 9. Gate charge Characteristics

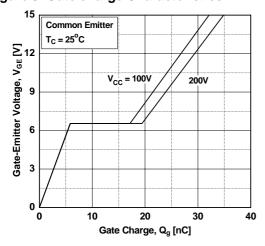


Figure 11. Turn-on Characteristics vs.

Gate Resistance

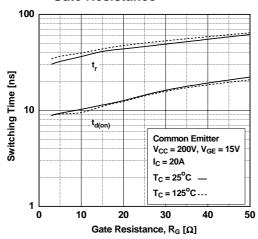


Figure 8. Capacitance Characteristics

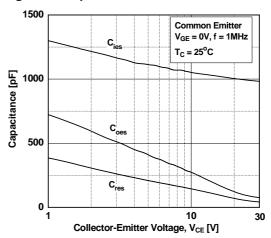


Figure 10. SOA Characteristics

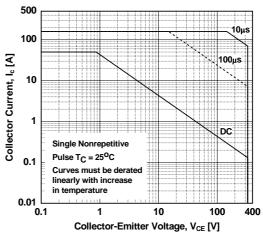


Figure 12. Turn-off Characteristics vs.
Gate Resistance

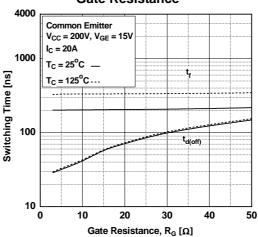


Figure 13. Turn-on Characteristics vs. Collector Current

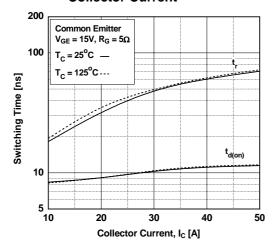


Figure 14. Turn-off Characteristics vs.
Collector Current

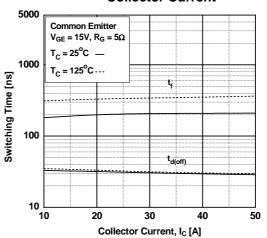


Figure 15. Switching Loss vs. Gate Resistance

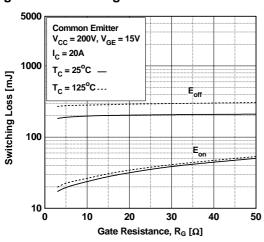


Figure 16. Switching Loss vs. Collector Current

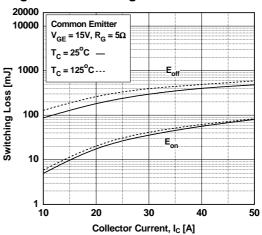


Figure 17. Turn off Switching SOA Characteristics

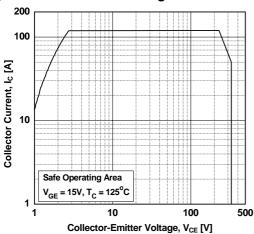
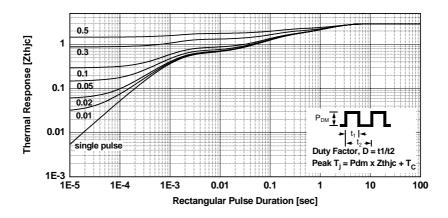
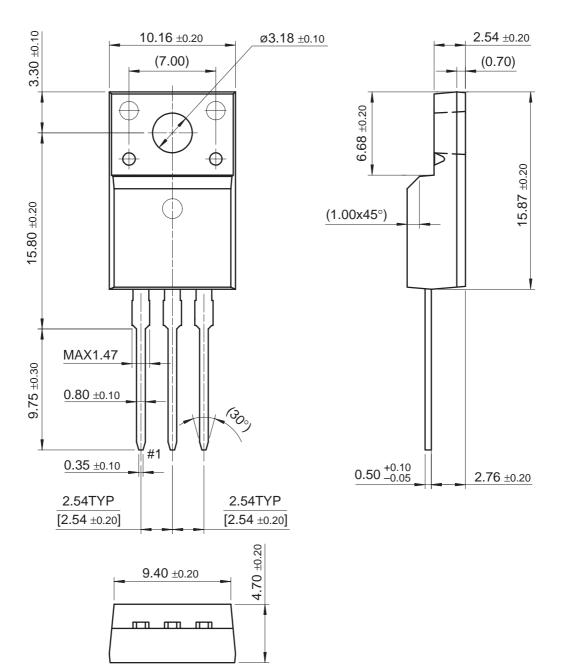


Figure 18.Transient Thermal Impedance of IGBT



Mechanical Dimensions

TO-220F



Dimensions in Millimeters





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